

# SN54LS139A, SN54S139, SN74LS139A, SN74S139A DUAL 2-LINE TO 4-LINE DECODERS/DEMULTIPLEXERS

SDLS013

DECEMBER 1972—REVISED MARCH 1988

- Designed Specifically for High-Speed: Memory Decoders Data Transmission Systems
- Two Fully Independent 2- to 4-Line Decoders/Demultiplexers
- Schottky Clamped for High Performance

## description

These Schottky-clamped TTL MSI circuits are designed to be used in high-performance memory-decoding or data-routing applications requiring very short propagation delay times. In high-performance memory systems, these decoders can be used to minimize the effects of system decoding. When employed with high-speed memories utilizing a fast-enable circuit, the delay times of these decoders and the enable time of the memory are usually less than the typical access time of the memory. This means that the effective system delay introduced by the Schottky-clamped system decoder is negligible.

The circuit comprises two individual two-line to four-line decoders in a single package. The active-low enable input can be used as a data line in demultiplexing applications.

All of these decoders/demultiplexers feature fully buffered inputs, each of which represents only one normalized load to its driving circuit. All inputs are clamped with high-performance Schottky diodes to suppress line-ringing and to simplify system design. The SN54LS139A and SN54S139 are characterized for operation range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN74LS139A and SN74S139A are characterized for operation from  $0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$ .

FUNCTION TABLE

INPUTS			OUTPUTS			
ENABLE	SELECT		Y0	Y1	Y2	Y3
$\overline{\text{G}}$	B	A				
H	X	X	H	H	H	H
L	L	L	L	H	H	H
L	L	H	H	L	H	H
L	H	L	H	H	L	H
L	H	H	H	H	H	L

H = high level, L = low level, X = irrelevant

SN54LS139A, SN54S139 . . . J OR W PACKAGE  
SN74LS139A, SN74S139A . . . D OR N PACKAGE

(TOP VIEW)



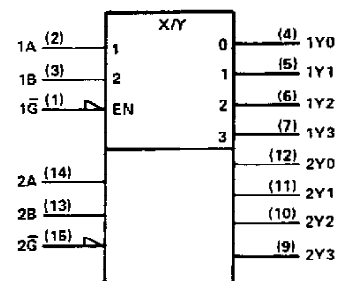
SN54LS139A, SN54S139 . . . FK PACKAGE

(TOP VIEW)



NC—No internal connection

## logic symbols (alternatives)†



†These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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# SN54LS139A, SN54S139, SN74LS139A, SN74S139A DUAL 2-LINE TO 4-LINE DECODERS/DEMULTIPLEXERS

logic diagram (positive logic)



Pin numbers shown are for D, J, N, and W packages.

## schematics of inputs and outputs



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, $V_{CC}$ (See Note 1)	7 V
Input voltage: 'LS139A	7 V
54S139, 74S139A	5.5 V
Operating free-air temperature range: SN54LS139A, SN54S139	-55°C to 125°C
SN74LS139A, SN74S139A	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

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## SN54LS139A, SN74LS139A DUAL 2-LINE TO 4-LINE DECODERS/DEMULTIPLEXERS

### recommended operating conditions

		SN54LS139A			SN74LS139A			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V <sub>IH</sub>	High-level input voltage	2			2			V
V <sub>IL</sub>	Low-level input voltage			0.7			0.8	V
I <sub>OH</sub>	High-level output current			-0.4			-0.4	mA
I <sub>OL</sub>	Low-level output current			4			8	mA
T <sub>A</sub>	Operating free-air temperature	-55		125	0		70	°C

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS <sup>†</sup>	SN54LS139A		SN74LS139A		UNIT		
		MIN	TYP <sup>‡</sup>	MAX	MIN		TYP <sup>‡</sup>	MAX
V <sub>IK</sub>	V <sub>CC</sub> = MIN, I <sub>I</sub> = -18 mA			-1.5		-1.5	V	
V <sub>OH</sub>	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, V <sub>IL</sub> = MAX, I <sub>OH</sub> = -0.4 mA	2.5	3.4		2.7	3.4	V	
V <sub>OL</sub>	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, V <sub>IL</sub> = MAX	I <sub>OL</sub> = 4 mA		0.25	0.4	0.25	0.4	V
		I <sub>OL</sub> = 8 mA				0.35	0.5	
I <sub>I</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 7 V			0.1		0.1	mA	
I <sub>IH</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.7 V			20		20	μA	
I <sub>IL</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.4 V			-0.4		-0.4	mA	
I <sub>OS</sub> <sup>§</sup>	V <sub>CC</sub> = MAX	-20		-100	-20	-100	mA	
I <sub>CC</sub>	V <sub>CC</sub> = MAX, Outputs enabled and open		6.8	11		6.8	11	mA

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

<sup>‡</sup> All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

<sup>§</sup> Not more than one output should be shorted at a time, and duration of the short circuit test should not exceed one second.

### switching characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C (see Note 2)

PARAMETER <sup>¶</sup>	FROM (INPUT)	TO (OUTPUT)	LEVELS OF DELAY	TEST CONDITIONS	SN54LS139A SN74LS139A			UNIT
					MIN	TYP	MAX	
t <sub>PLH</sub>	Binary Select	Any	2	R <sub>L</sub> = 2 kΩ, C <sub>L</sub> = 15 pF		13	20	ns
t <sub>PHL</sub>						22	33	ns
t <sub>PLH</sub>			3			18	29	ns
t <sub>PHL</sub>						25	38	ns
t <sub>PLH</sub>	Enable	Any	2			16	24	ns
t <sub>PHL</sub>						21	32	ns

<sup>¶</sup> t<sub>PLH</sub> = propagation delay time, low-to-high-level output

t<sub>PHL</sub> = propagation delay time, high-to-low-level output

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

  
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# SN54S139, SN74S139A

## DUAL 2-LINE TO 4-LINE DECODERS/DEMULTIPLIERS

### recommended operating conditions

		SN54S139			SN74S139A			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V <sub>IH</sub>	High-level input voltage	2			2			V
V <sub>IL</sub>	Low-level input voltage				0.8			V
I <sub>OH</sub>	High-level output current				-1			mA
I <sub>OL</sub>	Low-level output current				20			mA
T <sub>A</sub>	Operating free-air temperature	-55			125			°C

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54S139 SN74S139A			UNIT
		MIN	TYP‡	MAX	
V <sub>IK</sub>	V <sub>CC</sub> = MIN, I <sub>I</sub> = -18 mA	-1.2			V
V <sub>OH</sub>	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, V <sub>IL</sub> = 0.8 V, I <sub>OH</sub> = -1 mA	SN54S*	2.5	3.4	V
		SN74S*	2.7	3.4	
V <sub>OL</sub>	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, V <sub>IL</sub> = 0.8 V, I <sub>OL</sub> = 20 mA	0.5			V
I <sub>I</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 5.5 V	1			mA
I <sub>IH</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.7 V	50			μA
I <sub>IL</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.5 V	-2			mA
I <sub>OS</sub> §	V <sub>CC</sub> = MAX	-40	-100		mA
I <sub>CC</sub>	V <sub>CC</sub> = MAX, Outputs enabled and open	60 90			mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

§ Not more than one output should be shorted at a time, and duration of the short circuit test should not exceed one second.

### switching characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C (see Note 2)

PARAMETER†	FROM (INPUT)	TO (OUTPUT)	LEVELS OF DELAY	TEST CONDITIONS	SN54S139 SN74S139A			UNIT
					MIN	TYP	MAX	
t <sub>PLH</sub>	Binary Select	Any	2	R <sub>L</sub> = 280 Ω, C <sub>L</sub> = 15 pF	5	7.5	ns	
t <sub>PHL</sub>					6.5	10	ns	
t <sub>PLH</sub>			3		7	12	ns	
t <sub>PHL</sub>					8	12	ns	
t <sub>PLH</sub>	Enable	Any	2		5	8	ns	
t <sub>PHL</sub>					6.5	10	ns	

† t<sub>PLH</sub> = propagation delay time, low-to-high-level output

t<sub>PHL</sub> = propagation delay time, high-to-low-level output

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

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**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
76007012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	76007012A SNJ54LS 139AFK	<a href="#">Samples</a>
7600701EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7600701EA SNJ54LS139AJ	<a href="#">Samples</a>
7600701FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7600701FA SNJ54LS139AW	<a href="#">Samples</a>
7700401EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7700401EA SNJ54S139J	<a href="#">Samples</a>
7700401FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7700401FA SNJ54S139W	<a href="#">Samples</a>
JM38510/30702B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30702B2A	<a href="#">Samples</a>
JM38510/30702BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30702BEA	<a href="#">Samples</a>
JM38510/30702BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30702BFA	<a href="#">Samples</a>
JM38510/30702SEA	ACTIVE	CDIP	J	16	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30702SEA	<a href="#">Samples</a>
JM38510/30702SFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30702SFA	<a href="#">Samples</a>
M38510/30702B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30702B2A	<a href="#">Samples</a>
M38510/30702BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30702BEA	<a href="#">Samples</a>
M38510/30702BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30702BFA	<a href="#">Samples</a>
M38510/30702SEA	ACTIVE	CDIP	J	16	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30702SEA	<a href="#">Samples</a>
M38510/30702SFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30702SFA	<a href="#">Samples</a>
SN54LS139AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS139AJ	<a href="#">Samples</a>
SN54S139J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54S139J	<a href="#">Samples</a>

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS139AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS139A	<a href="#">Samples</a>
SN74LS139ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS139A	<a href="#">Samples</a>
SN74LS139ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS139A	<a href="#">Samples</a>
SN74LS139AN	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS139AN	<a href="#">Samples</a>
SN74LS139ANE4	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS139AN	<a href="#">Samples</a>
SN74LS139ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS139A	<a href="#">Samples</a>
SN74S139AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	S139A	<a href="#">Samples</a>
SN74S139AN	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74S139AN	<a href="#">Samples</a>
SNJ54LS139AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	76007012A SNJ54LS 139AFK	<a href="#">Samples</a>
SNJ54LS139AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7600701EA SNJ54LS139AJ	<a href="#">Samples</a>
SNJ54LS139AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7600701FA SNJ54LS139AW	<a href="#">Samples</a>
SNJ54S139J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7700401EA SNJ54S139J	<a href="#">Samples</a>
SNJ54S139W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7700401FA SNJ54S139W	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of  $\leq 1000$ ppm threshold. Antimony trioxide based flame retardants must also meet the  $\leq 1000$ ppm threshold requirement.

(3) **MSL, Peak Temp.** - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) **Lead/Ball Finish** - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF SN54LS139A, SN54LS139A-SP, SN74LS139A :**

● Catalog: [SN74LS139A](#), [SN54LS139A](#)

● Military: [SN54LS139A](#)

● Space: [SN54LS139A-SP](#)

**NOTE: Qualified Version Definitions:**

● Catalog - TI's standard catalog product

● Military - QML certified for Military and Defense Applications

- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application



**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS139ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS139ANSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS139ADR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS139ANSR	SO	NS	16	2000	367.0	367.0	38.0

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP2-F16

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - Falls within JEDEC MS-004

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4040047-6/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  -  C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  -  D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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